ABSTRACT

A double-sided molding method utilizing a protective film which is not separated from a resin pattern subjected to protection during a process, does not cause a failure, and does not leave an adhesive when removed, and a molded product of the same are provided. This double-sided molding method is for forming a first resin pattern 110 on a first surface 11 of a substrate 1 and for forming a second resin pattern 120 on a second surface 12 of the substrate 1, and includes a protective film pasting process of pasting, on the first resin pattern 110, a silicone-rubber-layer side of a protective film 2 including a silicone-rubber layer, and a second resin pattern molding process of forming the second resin pattern 120 on the second surface 12 after the protective film pasting process.